

**AMENDMENTS TO THE CLAIMS**

1-27. (Cancelled)

28. (New) A semiconductor package comprising:  
a substrate having a plurality of bond fingers mounted thereon;  
a semiconductor chip having a plurality of bond pads;  
a plurality of solder ball pads mounted on the substrate;  
a first bond finger having a conductive circuit pattern connecting it to one of the solder ball pads;  
a second bond finger having a first wire bonding unit connecting it to one of the bond pads; and  
a second wire bonding unit connecting the first and second bond fingers thereby connecting said one bond pad to said one solder ball pad.

29. (New) The semiconductor package of claim 28 wherein there is no conductive circuit pattern between the second bond finger and any of the solder ball pads.

30. (New) The semiconductor package of claim 29 where there is no wire bonding unit between the first bond finger and any of the bond pads.

31. (New) The semiconductor package of claim 28 where there is no wire bonding unit between the first bond finger and any of the bond pads.

32. (New) The semiconductor package of claim 28, further comprising:  
an encapsulant for encapsulating the semiconductor chip and wire bonding units.

33. (New) The semiconductor package of claim 32, further comprising:  
a solder ball connected to said one solder ball pad.

34. (New) The semiconductor package of claim 28, wherein the substrate is a single-layer substrate on which the circuit pattern is formed.

35. (New) The semiconductor package of claim 28, wherein the substrate is a double-layer substrate or a multi-layer substrate.
36. (New) The semiconductor package of claim 28, wherein a solder mask is not formed on the first bond finger.
37. (New) The semiconductor package of claim 28, wherein the second wire bonding unit is formed over the substrate.
38. (New) The semiconductor package of claim 28, wherein the second wire bonding unit is formed on an outer region of the substrate on which the semiconductor chip is mounted.
39. (New) The semiconductor package of claim 28, wherein the second wire bonding unit is one unit or a plurality of units.
40. (New) The semiconductor package of claim 28, wherein the semiconductor chip is attached to the substrate using an adhesive.
41. (New) The semiconductor package of claim 28, wherein the first bond finger is made by further extending the printed circuit pattern on the substrate.
42. (New) The semiconductor package of claim 28, wherein the first bond finger has the same pad shape as that of the second bond finger.
43. (New) A semiconductor package comprising:  
a substrate having a plurality of bond fingers mounted thereon;  
a plurality of solder ball pads mounted on the substrate;  
a first conductive circuit pattern connected to one of the solder ball pads;  
a second conductive circuit pattern connected to one of the bond fingers; and  
a wire bonding unit connecting the first and second conductive circuit patterns thereby connecting said one bond pad to said one solder ball pad.

44. (New) The semiconductor package of claim 43, further comprising:  
an encapsulant for encapsulating the semiconductor chip and the wire bonding unit.

45. (New) The semiconductor package of claim 44, further comprising:  
a solder ball connected to the said one solder ball pad.

46. (New) The semiconductor package of claim 43, wherein the first and second  
circuit patterns each have a width that enables wire bonding to be performed thereon.